



## Material Content Data Sheet



<b>Sales Product Name</b>		BSC031N06NS3 G		<b>Issued</b>		21. October 2018		
<b>MA#</b>		MA002355530						
<b>Package</b>		PG-TDSON-8-39		<b>Weight*</b>		114.33 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.425	3.87	3.87	38706	38706
leadframe	inorganic material	phosphorus	7723-14-0	0.015	0.01		127	
	non noble metal	iron	7439-89-6	0.048	0.04		423	
	non noble metal	copper	7440-50-8	48.352	42.31	42.36	422915	423465
	non noble metal	copper	7440-50-8	0.072	0.06	0.06	630	630
wire	non noble metal	copper	7440-50-8	0.072	0.06	0.06	630	630
encapsulation	organic material	carbon black	1333-86-4	0.078	0.07		680	
	plastics	epoxy resin	-	6.142	5.37		53724	
	inorganic material	silicondioxide	60676-86-0	32.655	28.56	34.00	285619	340023
leadfinish	non noble metal	tin	7440-31-5	1.520	1.33	1.33	13295	13295
plating	noble metal	silver	7440-22-4	0.158	0.14	0.14	1386	1386
solder	non noble metal	tin	7440-31-5	0.070	0.06		610	
	noble metal	silver	7440-22-4	0.087	0.08		762	
	non noble metal	lead	7439-92-1	3.328	2.91	3.05	29111	30483
heatspreader	inorganic material	phosphorus	7723-14-0	0.000	0.00		1	
	non noble metal	iron	7439-89-6	0.000	0.00		3	
	non noble metal	copper	7440-50-8	0.297	0.26	0.26	2599	2603
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		44	
	non noble metal	iron	7439-89-6	0.017	0.01		148	
	noble metal	silver	7440-22-4	0.150	0.13		1312	
	non noble metal	copper	7440-50-8	16.910	14.79	14.93	147905	149409
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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